Press Release

No Bleed, Non-Conductive Die Attach Adhesive for Stacked Packages Now Available from Henkel

Hysol® QMI538NB Delivers Excellent Thermal Stability and Superior Adhesion Strength

The latest in a series of new die attach products from the world's leading electronics materials formulator and supplier, Henkel announces the commercial availability of Hysol® QMI538NB. The non-conductive die attach adhesive is a PTFE-filled paste with low viscosity, reduced resin bleed even on open channels and is designed specifically for use with SCSPs or other stacked packages.

Hysol QMI538NB's unique formulation has been designed to provide hydrophobic properties while also delivering stability at extremely high temperatures with no material deterioration. Product testing of this material confirms its high reliability and exceptional performance even after multiple exposures to reflow temperatures up to 260°C, and its low modulus and low stress make it highly resistant to warpage. These characteristics enable Hysol QMI538NB to produce void free bondlines with excellent adhesion strength to a wide variety of surfaces, including solder resist, flexible tape, bare silicon, silicon nitride, polyimide and various die passivations. It is PTFE-filled and does not scratch the most delicate die passivations.

Just like other materials in the QMI portfolio, Hysol QMI538NB enhances productivity and provides increased reliability. As compared to conventional oven cured adhesives, Hysol QMI538NB is designed to achieve significant cycle time improvement due to Henkel's patented *Skip*Cure™ process. The product can be *Skip*Cured™ on the diebonder or on the wirebonder preheater, the versatility of which allows the user to begin production using conventional oven cure and then switch to *Skip*Cure, enabling significant cost reductions.

Hysol QMI538NB can also be converted into a controlled collapse spacer paste (CCSP) to control bondlines and fillet heights. Because the spacers do not alter the material properties, manufacturers who qualify Hysol QMI538NB first can easily transfer to its CCSP version and can expect package reliability improvement.

This unique material is JEDEC Level 3 260°C qualified. For more information on Hysol QMI538NB or any of the materials in Henkel's Hysol QMI product suite, call (949) 789-2500 or visit www.electronics.henkel.com.

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About the electronics group of Henkel

Henkel is the world's leading and most progressive provider of qualified, compatible material sets for semiconductor packaging, board level assembly and advanced soldering solutions. Through its Hysol, Loctite and Multicore brands, and its global customer support infrastructure, the electronics group of Henkel delivers world-class materials products, process expertise and total solutions across the board to enable tomorrow's electronic industry.

The Henkel Group operates in three strategic business areas – Home Care, Personal care, and Adhesives, Sealants and Surface Treatments of which the electronics group is part, serving transportation, electronics, aerospace, metal, durable goods, consumer goods, maintenance and repair and packaging industries, and offering a broad range of products for the craftsman and consumer. With brands and advanced technologies, Henkel makes people's lives easier, better, and more beautiful. 50,000 employees work for the Henkel Group worldwide. People in 125 countries around the world trust in brands and technologies from Henkel – "A Brand like a Friend".

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